



OCT 28 2004

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To:	USPTO	From:	Alfred W. Froebrich
Fax:	703 872-9306	Pages:	9 (total number of pages)
Re:	U.S. Patent Application No. 09/736,553	Date:	Thursday, October 28, 2004

☐ Confirmation will follow☒ No confirmation to follow

Attached please find an amendment in the above-referenced application.

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OCT 28 2004

Attorney Docket # 4797-9

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Manfred SCHINGNITZ et al.

Serial No.: 09/736,553

Filed: December 13, 2000

For: Process For The Utilization Of Halogen
Containing Remainers And Waste Materials

Examiner: Nguyen, Ngoc Yen
Group Art: 1754

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to fax number 703 872-9306, at the United
States Patent and Trademark Office, on
October 28, 2004
(Date of Deposit)

Alfred W. Froeblich

Name of applicant, assignee or Registered
Representative


Signature

October 28, 2004

Date of Signature

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

SIR:

In response to the final Office Action dated July 28, 2004, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.